

## CLAIMS

1. A semiconductor module comprising:

a semiconductor device provided with a semiconductor  
5 chip; and

a conductive cover for electromagnetic shielding bonded  
to the semiconductor device via an adhesive coat;

wherein the conductive cover includes a surface facing  
the adhesive coat, the surface being formed with a convex  
10 portion protruding toward the adhesive coat,

wherein around the convex portion, a space is formed for  
filling in adhesive to form the adhesive coat.

2. The semiconductor module according to claim 1, comprising

15 three or more convex portions arranged nonlinearly.

3. The semiconductor module according to claim 1, comprising  
two or more elongated convex portions having center axes  
non-collinear to each other.

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4. The semiconductor module according to claim 1, wherein the  
semiconductor device includes a surface facing the adhesive  
coat, the surface being formed with a recess,

wherein at least a part of the convex portion is positioned  
25 on a portion other than the recess.

5. The semiconductor module according to any one of claims

1 to 4, wherein the conductive cover is made of a metal, and  
the convex portion is formed by embossing.

6. The semiconductor module according to any one of claims  
5 1 to 4,

wherein the semiconductor device includes a light emitting element capable of generating infrared rays, a light receiving element capable of receiving and detecting infrared rays, and an IC chip,

10 wherein the semiconductor module is an infrared communication module capable of transmitting and receiving infrared rays.

7. A semiconductor module comprising:

15 a semiconductor device provided with a semiconductor chip; and

a conductive cover for electromagnetic shielding bonded to the semiconductor device via an adhesive coat;

20 wherein the semiconductor device includes a surface facing the adhesive coat, the surface being formed with a convex portion protruding toward the adhesive coat,

wherein around the convex portion, a space is formed for filling in adhesive to form the adhesive coat.